

Product Specification

Product:	Conductive Silver Paste
Part Number:	01L-2609S

Application Scope :

Single-component conductive paste series, a conductive silver paste with reliable adhesion for chip fixation. This paste is suitable for bonding various chips onto substrates such as circuit boards, glass, and ceramics, exhibiting excellent compatibility with the substrate without sagging. Electrodes fabricated with this paste exhibit a glossy, fine appearance and dense structure after curing.

Usage Conditions :

Substrate	Circuits, glass, ceramics, metals
Usage Method	Adhesive and dispense
Leveling	Let it level at room temperature for 5-10 minutes (adjust time based on actual leveling conditions).
Solidify	Furnace drying at 120–150°C for 30 minutes The curing temperature can be within the range of 130-180°C, and the curing time can be determined based on actual conditions.
Thinner	ST-1001

Characteristics :

1. Paste Characteristics :

Characteristic	Standard	Test Method And Conditions
1 Fineness	$\leq 15\mu\text{m}$	FOG test
2 Viscosity	120-320Pa.s	Brookfield HBT (Boli Fei) viscometer, rotor SC4-14/6R, 10 rpm, with adjustable viscosity at $25\pm 1^\circ\text{C}$ according to user requirements.
3 Solid Content	70	Silver

2. Characteristics After Curing :

Under the condition of 1 sintering, Check fired film produced under the conditions specified in 1)

Characteristics		Standard	Test Method And Conditions
4	Resistivity	$\leq 30\text{m}\Omega/\square$	
5	Hardness	4H	Pencil hardness
6	Shear Strength	12Mpa	

Save Conditions And Validity Period :

The product shall be stored in a sealed container at an ambient temperature of 5-15°C, with a shelf life of six months from the date of shipment.

Packaging Method :

Standard packaging, 1000g/can; samples are available in 200g small can packaging.